




Product Specification

AU OPTRONICS CORPORATION

() Preliminary Specifications

(V) Final Specifications

Module	10.1''(10.01'') WXGA 16:10 Color TFT-LCD
Model Name	B101EAN01.5 (H/W: 0A) LCM
Note ()	<i>LED Backlight with driving circuit design</i>

Customer	Date
Checked & Approved by	Date
Note: This Specification is subject to change without notice.	

Approved by	Date
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Record of Revision

Version and Date	Page	Old description	New Description	Remark
0.1 08/14/2013		First Edition for Customer		
0.2 09/13/2013	12,23		Modify Absolute Ratings of Environment Add Panel Reliability Test	
0.3 10/02/2013	26,27		Modify 9.1 & 9.2 Label Add 10.1 EDID Description	
0.4 10/23/2013	20	MIPI Pin 28 “NC”, Not Connection	MIPI Pin 28 “GND”, Ground	
0.5 11/14/2013	24	Front View Drawing Upper Pol Size&Position	Front View Drawing Upper Pol Size&Position	
0.6 11/29/2013	11,22		Functional Block Diagram (Add P Gamma) Power ON/OFF Sequence (No SMBUS)	
0.7 12/17/2013	18		Add 5.2 Backlight Unit 5.2.1 LED characteristics	
0.8 01/09/2014	06 18		Update 2.2 Optical Characteristics 5.2 Backlight Unit	
0.9 04/01/2014	23		Update 6.4 Power ON/OFF Sequence	
0.10 04/25/2014	18 20 21		Update 5.2.2 Backlight input signal characteristics Update 6.2.2 MIPI Pin Assignment	
0.11 2014/04/28	05	General Specification Physical Size : Length & Width	Length : Min. : 227.42 mm Width : Min . : 147.5 mm	
0.12 2014/05/05	06	Response Time	Response Time : 38 msec (Max.)	
0.13 2014/05/20	21		Update 6.3.1 Timing Characteristics Horizontal Section: Period(TH) : 1,340 Min. ; 1,480 Typ. Blanking(THB) : 60 Min.	
0.14 2014/06/03	27		Update 9.1 Shipping Label Format	
0.15 2014/07/18	20 21 23		Update 6.2.2 MIPI Pin Assignment Update 6.4 Power ON/OFF Sequence	
0.16 2014/07/30	05 25 27	Width : 147.8 +/- 0.3mm	Width : 148.3 +/- 0.3mm Update 8.1 Standard Front View Update Label HW : 0A -> 1A	

1. Handling Precautions

- 1) Since front polarizer is easily damaged, pay attention not to scratch it.
- 2) Be sure to turn off power supply when inserting or disconnecting from input connector.
- 3) Wipe off water drop immediately. Long contact with water may cause discoloration or spots.
- 4) When the panel surface is soiled, wipe it with absorbent cotton or other soft cloth.
- 5) Since the panel is made of glass, it may break or crack if dropped or bumped on hard surface.
- 6) Since CMOS LSI is used in this module, take care of static electricity and insure human earth when handling.
- 7) Do not open or modify the Module Assembly.
- 8) Do not press the reflector sheet at the back of the module to any directions.
- 9) At the insertion or removal of the Signal Interface Connector, be sure not to rotate nor tilt the Interface Connector of the TFT Module.
- 10) After installation of the TFT Module into an enclosure (Notebook PC Bezel, for example), do not twist nor bend the TFT Module even momentarily. At designing the enclosure, it should be taken into consideration that no bending/twisting forces are applied to the TFT Module from outside. Otherwise the TFT Module may be damaged.
- 11) Disconnecting power supply before handling LCD modules, it can prevent electric shock, DO NOT TOUCH the electrode parts, cables, connectors and LED circuit part of TFT module that a LED light bar build in as a light source of back light unit. It can prevent electrostatic breakdown.



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2. General Description

B101EAN01.5 is a 10.1 inch-wide Color Active Matrix Liquid Crystal Display composed of a TFT LCD panel, a driver circuit, and LED backlight system. The display supports the 16:10 WXGA, 1280(H) x800(V) screen and 16.7M colors (RGB 6-bits data driver with FRC). All input signals are MIPI interface compatible.

2.1 General Specification

The following items are characteristics summary on the table at 25 °C condition:

Items	Unit	Specifications			
Screen Diagonal	[mm]	255.85 (10.07 inch)			
Active Area	[mm]	216.96(H) x 135.6(V)			
Pixels H x V		1280 x 3(RGB) x 800			
Pixel Pitch	[mm]	0.1695 X 0.1695			
Pixel Format		R.G.B. Vertical Stripe			
Display Mode		AHVA, Normally Black			
White Luminance (ILED=24mA) (Note: ILED is LED current)	[cd/m2]	350 typ. (5 points average) 295 min. (5 points average)			
Luminance Uniformity		1.25 max. (5 points)			
Contrast Ratio		TYP. 800:1 / Min 600:1			
Response Time	[ms]	Typ. 30 (White to black)			
Nominal Input Voltage VDD	[Volt]	3.3V typ			
Power Consumption	[Watt]	3.05 W(Max) w/ LED driver			
Weight	[Grams]	145g Max			
Physical Size Include bracket	[mm]		Min	Typ	Max
		Length	227.42	227.72	228.02
		Width	148.0	148.3	148.6
		Thickness Panel Side		2.37	2.6
		Thickness PCBA Side			4.6
Electrical Interface		MIPI			
Glass Thickness	[mm]	0.25/0.25 (w/o PF)			
Surface Treatment (panel only)		HC (Glare)			



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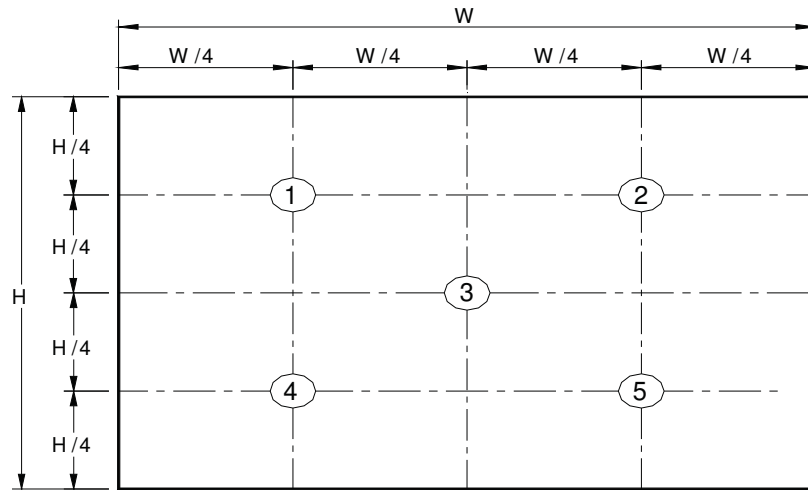
Support Color		16.7M colors (RGB 6-bit +FRC)
Temperature Range Operating	[°C] [°C]	0 to + 50°C -20 to +60°C
RoHS Compliance		RoHS Compliance

2.2 Optical Characteristics

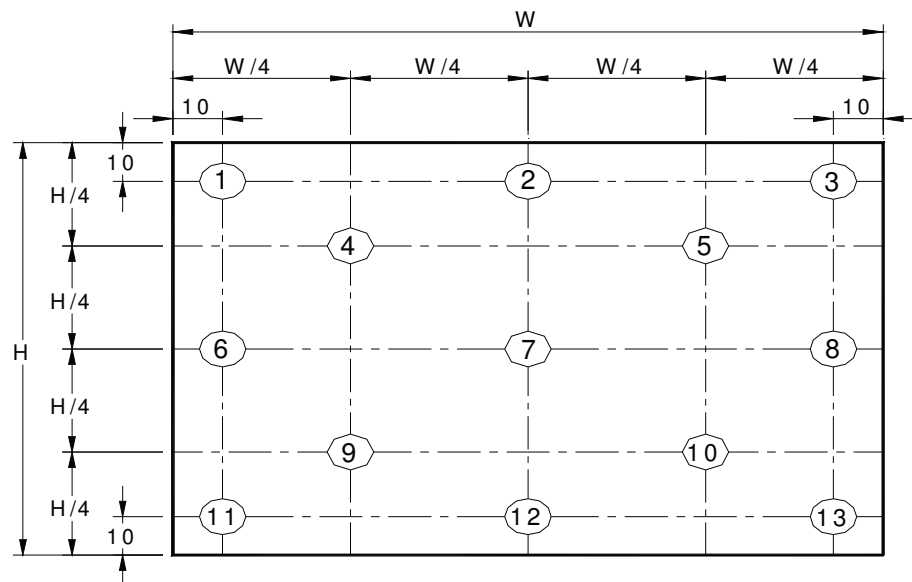
The optical characteristics are measured under stable conditions at 25°C (Room Temperature) :

Item		Symbol	Conditions	Min.	Typ.	Max.	Unit	Note
White Luminance I _{LED} =24mA			5 points average	295	350	-	cd/m ²	1, 4, 5.
Viewing Angle		θ_R	Horizontal (Right) CR = 10 (Left)		85	-	degree	4, 9
		θ_L			85	-		
		ϕ_H	Vertical (Upper) CR = 10 (Lower)		85	-		
		ϕ_L			85	-		
Brightness Uniformity		δ_{5P}	5 Points			1.25		1, 3, 4
Brightness Uniformity		δ_{13P}	13 Points			1.50		1, 3, 4
Contrast Ratio		CR		600	800	-		4, 6
Response Time		T _{RT}	Rising + Falling	-	30	38	msec	4, 8
Color / Chromaticity Coordinates	Red	R _x	CIE 1931	0.568	0.598	0.628		4
		R _y		0.314	0.344	0.374		
	Green	G _x		0.296	0.326	0.356		
		G _y		0.554	0.584	0.614		
	Blue	B _x		0.124	0.154	0.184		
		B _y		0.100	0.130	0.160		
	White	W _x		0.283	0.313	0.343		
		W _y		0.299	0.329	0.359		
NTSC		%				50		

Note 1: 5 points position (Ref: Active area)



Note 2: 13 points position (Ref: Active area)



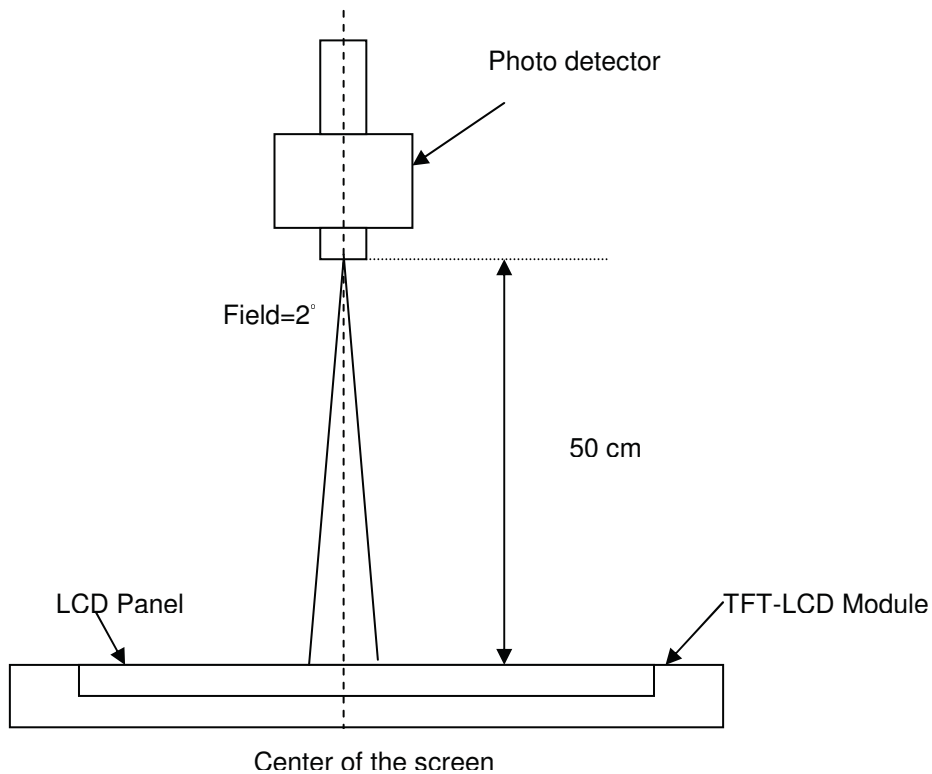
Note 3: The luminance uniformity of 5 or 13 points is defined by dividing the maximum luminance values by the minimum test point luminance

$$\delta_{w5} = \frac{\text{Maximum Brightness of five points}}{\text{Minimum Brightness of five points}}$$

$$\delta_{w13} = \frac{\text{Maximum Brightness of thirteen points}}{\text{Minimum Brightness of thirteen points}}$$

Note 4: Measurement method

The LCD module should be stabilized at given temperature for 30 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 30 minutes in a stable, windless and dark room, and it should be measured in the center of screen.



Note 5 : Definition of Average Luminance of White (Y_L):

Measure the luminance of gray level 63 at 5 points , $Y_L = [L (1)+ L (2)+ L (3)+ L (4)+ L (5)] / 5$

$L (x)$ is corresponding to the luminance of the point X at Figure in Note (1).

Note 6 : Definition of contrast ratio:

Contrast ratio is calculated with the following formula.

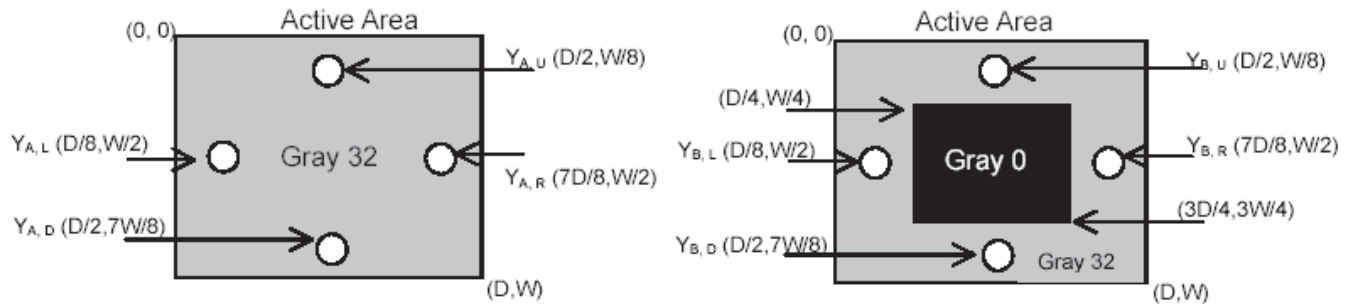
$$\text{Contrast ratio (CR)} = \frac{\text{Brightness on the "White" state}}{\text{Brightness on the "Black" state}}$$

Note 7 : Definition of Cross Talk (CT)

$$CT = |Y_B - Y_A| / Y_A \times 100 (\%)$$

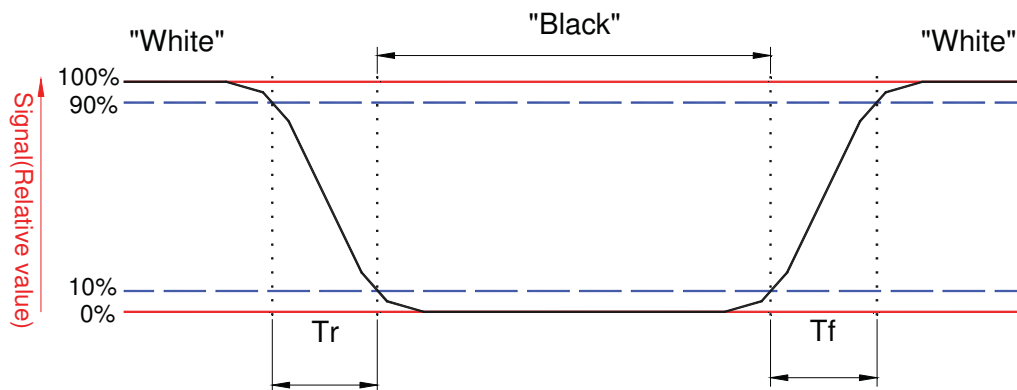
Where

Y_A = Luminance of measured location without gray level 0 pattern (cd/m²)



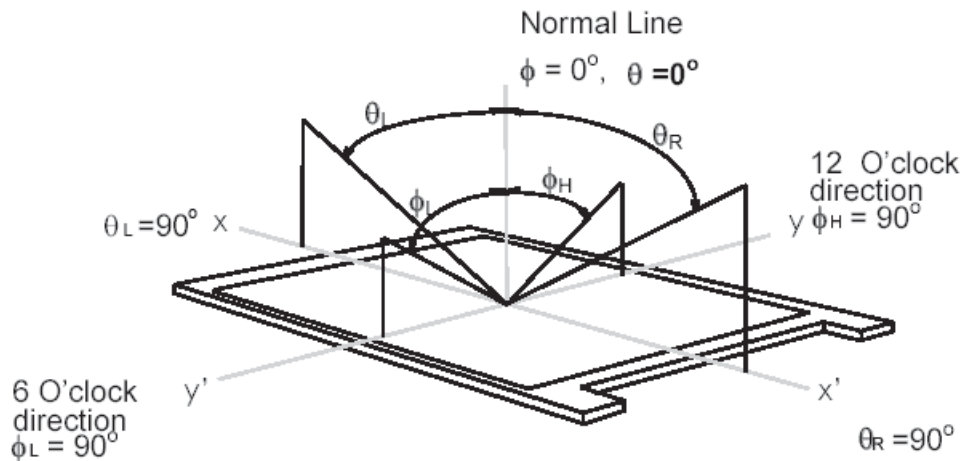
Note 8: Definition of response time:

The output signals of BM-7 or equivalent are measured when the input signals are changed from "Black" to "White" (falling time) and from "White" to "Black" (rising time), respectively. The response time interval between the 10% and 90% of amplitudes. Refer to figure as below.



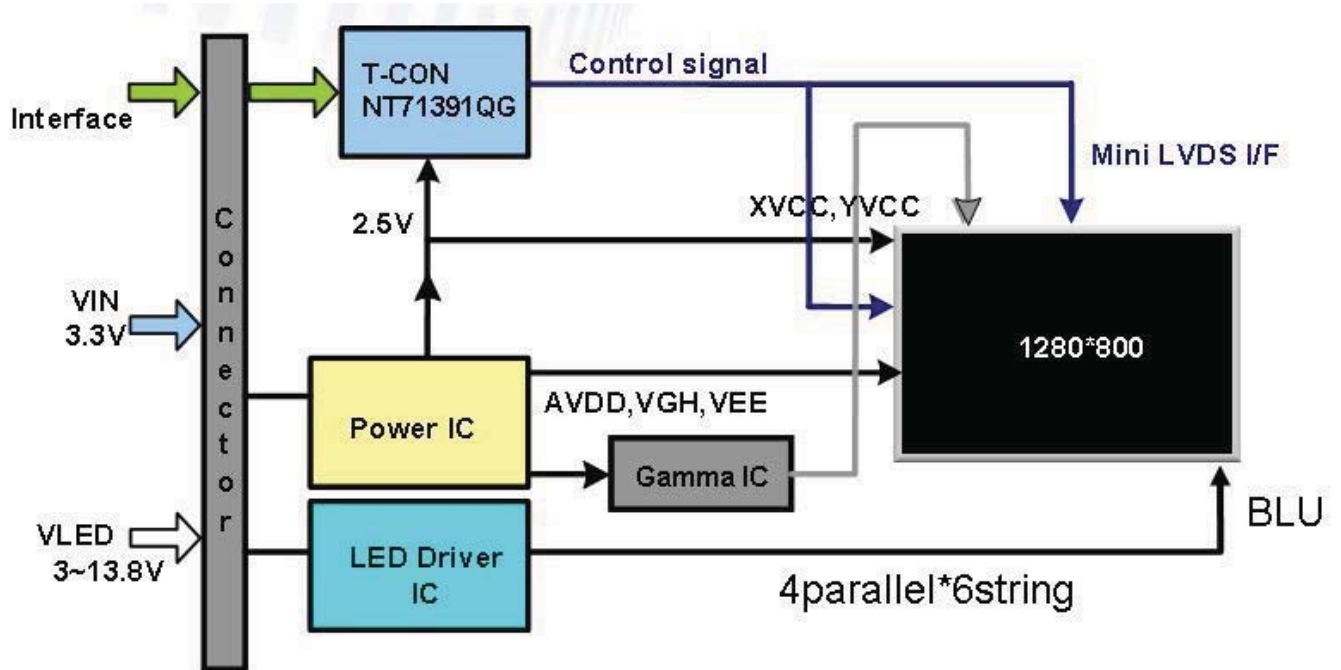
Note 9. Definition of viewing angle

Viewing angle is the measurement of contrast ratio ≥ 10 , at the screen center, over a 180° horizontal and 180° vertical range (off-normal viewing angles). The 180° viewing angle range is broken down as follows; 90° (θ) horizontal left and right and 90° (Φ) vertical, high (up) and low (down). The measurement direction is typically perpendicular to the display surface with the screen rotated about its center to develop the desired measurement viewing angle.



3. Functional Block Diagram

The following diagram shows the functional block of the 10.1 inches wide Color TFT/LCD.



4. Absolute Maximum Ratings

An absolute maximum rating of the module is as following:

4.1 Absolute Ratings of TFT LCD Module

Item	Symbol	Min	Max	Unit	Conditions
Logic/LCD Drive Voltage	Vin	-0.3	+4.0	[Volt]	Note 1,2

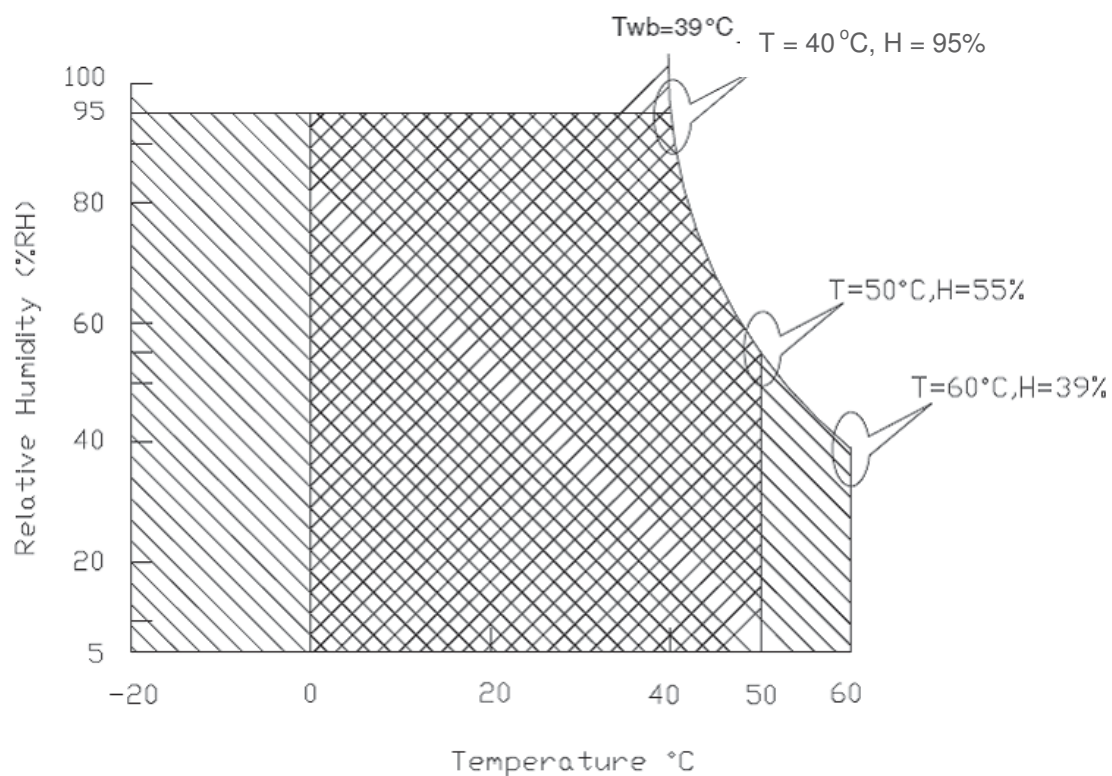
4.2 Absolute Ratings of Environment

Item	Symbol	Min	Max	Unit	Conditions
Operating Temperature	TOP	0	+50	[°C]	Note 3
Operation Humidity	HOP	0	90	[%RH]	Note 3
Storage Temperature	TST	-20	+60	[°C]	Note 3


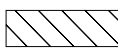
Note 1: At Ta (25°C)

Note 2: Permanent damage to the device may occur if exceed maximum values

Note 3: For quality performance, please refer to AUO IIS (Incoming Inspection Standard).



Operating Range 

Storage Range  + 

5. Electrical Characteristics

5.1 TFT LCD Module

5.1.1 Power Specification

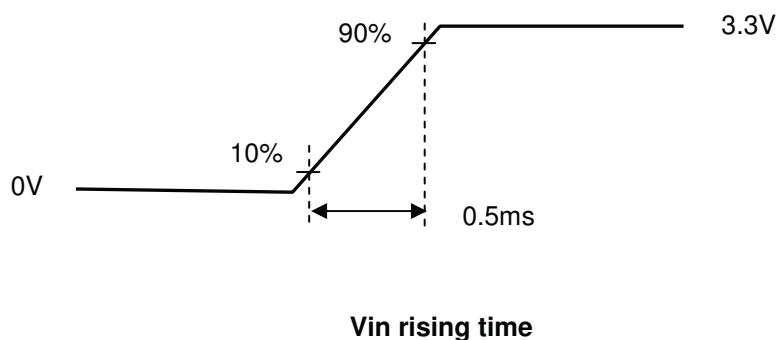
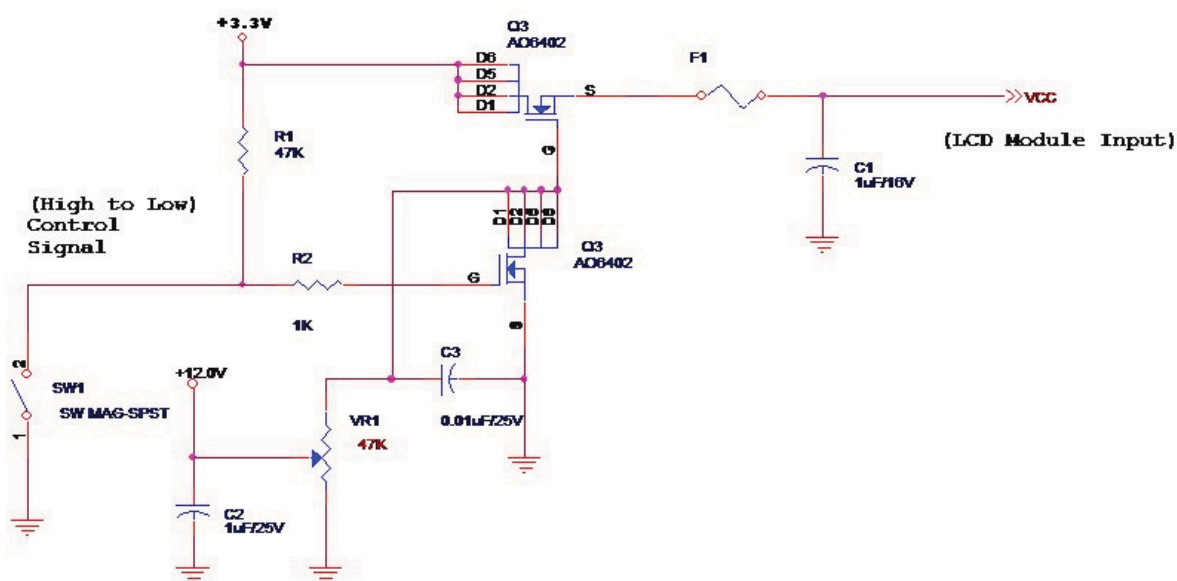
Input power specifications are as follows;

The power specification are measured under 25°C and frame frequency under 60Hz

Symble	Parameter	Min	Typ	Max	Units	Note
VDD	Logic/LCD Drive Voltage	3.1	-	3.6	[Volt]	
PDD	VDD Power	-	-	0.85	[Watt]	Note 1
IDD	IDD Current	-	-	240	[mA]	Note 1
IRush	Inrush Current	-	-	2000	[mA]	Note 2
VDDrp	Allowable Logic/LCD Drive Ripple Voltage	-	-	100	[mV] p-p	

Note 1 : Maximum Measurement Condition : White Pattern at 3.3V driving voltage. ($P_{\max} = V_{3.3} \times I_{\text{white}}$)

Note 2 : Measure Condition



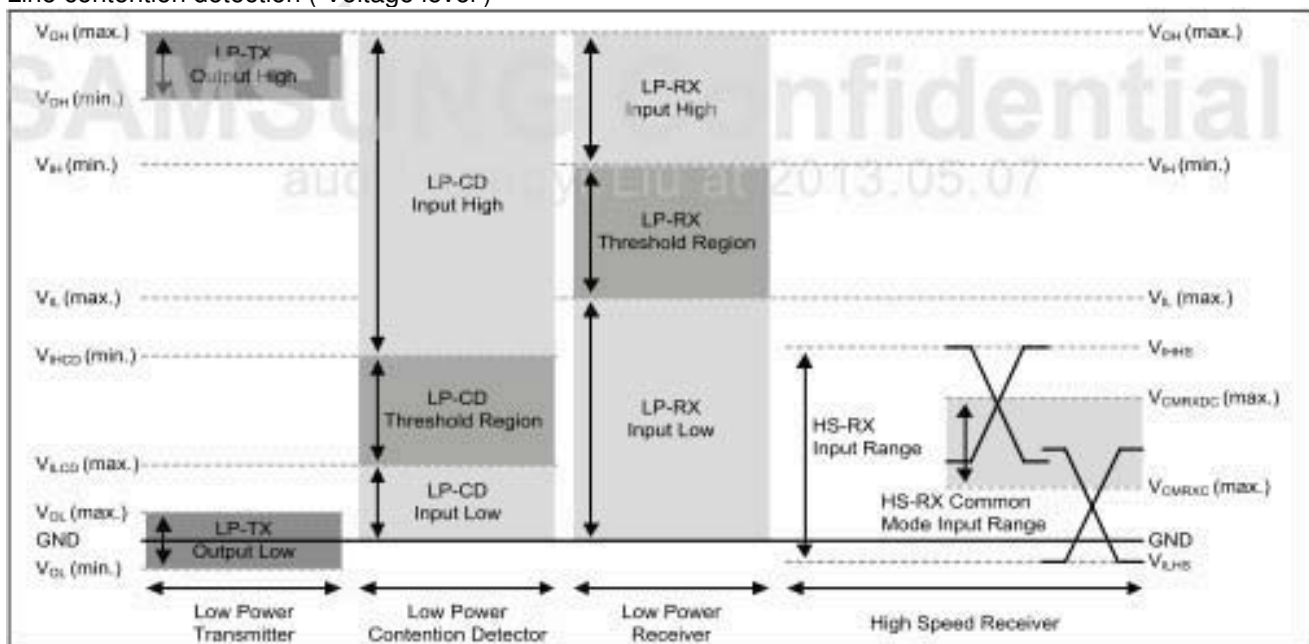
5.1.2 Signal Electrical Characteristics

Input signals shall be low or High-impedance state when VDD is off.

MIPI DC Characteristics are as follows;

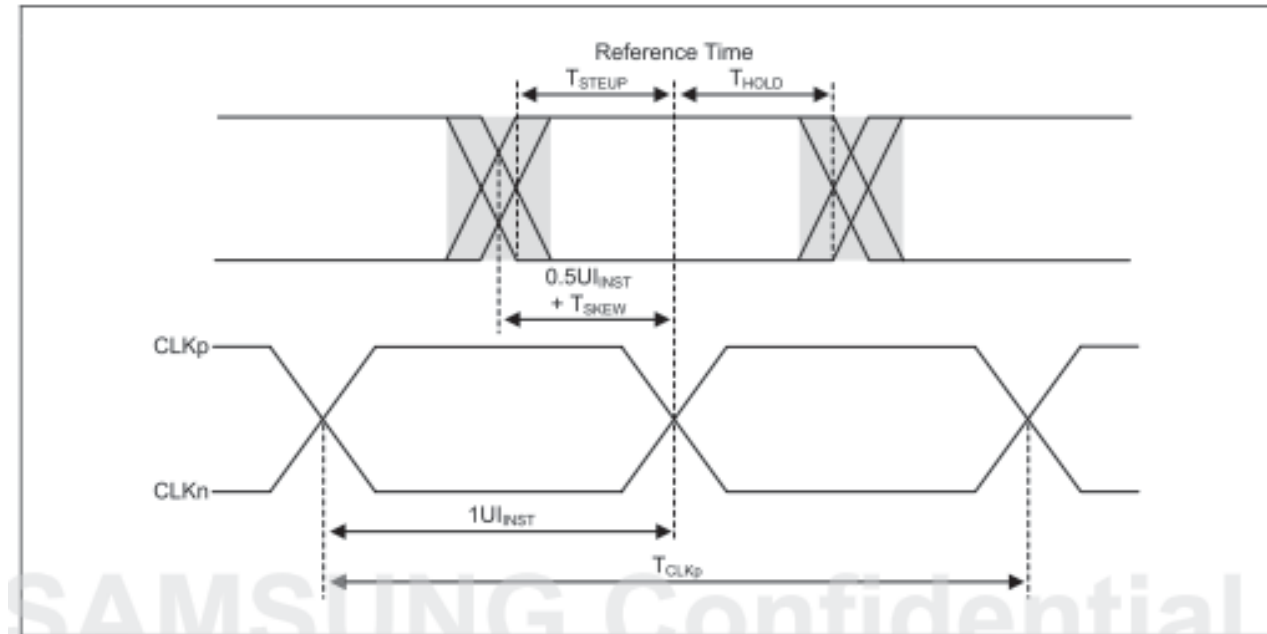
MIPI Receiver Differential Input (DC Characteristics)						
Symbol	Parameter	Parameter	Min	Typ	Max	Unit
LP_CD	Logic 1 contention threshold	VIHCD	450	---	---	mV
	Logic 0 contention threshold	VILCD	---	---	200	mV
HS_RX	Common-mode voltage(HS Rx mode)	VCMRX(DC)	70	---	330	mV
	Differential input high threshold (HS Rx mode)	VIDTH	---	---	70	mV
	Differential input low threshold (HS Rx mode)	VIDTL	-70	---	---	mV
	Single-end input high voltage (HS Rx mode)	VIHHS	---	---	460	mV
	Single-end input low voltage (HS Rx mode)	VILHS	-40	---	---	mV
	Single-ended threshold for HS termination enable	VTERM-EN	---	---	450	mV
	Differential input impedance	ZID	80	100	125	Ω
LP_RX	Logic 1 input voltage (LP Rx mode)	VIH	880			mV
	Logic 0 input voltage (LP Rx mode)	VIL			550	mV
	Input hysteresis	VHYST	25	---	---	mV
LP_TX	Output high level (LP Tx mode)	VOH	1.1	1.2	1.3	V
	Output low level (LP Tx mode)	VOL	-50		50	mV
	Output impedance of LP transmitter	ZOLP	110	---	---	Ω

Line contention detection (Voltage level)



MIPI High-Speed Data-clock Timing

Host sends a differential clock signal to the IC for data sampling. This signal is a DDR (half-rate) clock and has one transition per data bit time. The timing relationship of the DDR Clock differential signal to the Data differential signal is shown in following figure.



Symbol	Parameter	Min	Typ	Max	Unit	Notes
$T_{SKEW[TX]}$	Data to Clock Skew (measured at transmitter)	-0.15	---	0.15	---	1
$T_{SETUP[RX]}$	Data to Clock Setup Time (receiver)	0.15	---	---	UI_{INST}	2, 3
$T_{HOLD[RX]}$	Data to Clock Hold Time (receiver)	0.15	---	---	UI_{INST}	2, 3

Note:

1. Total silicon and package delay budget of $0.3 \cdot UI_{INST}$
2. Total setup and hold window for receiver of $0.3 \cdot UI_{INST}$
3. $T_{SETUP[RX]}$ and $T_{HOLD[RX]}$ without FPCB and connector and guaranteed by design

The timing definitions are listed in below,

Parameter	Description	Min	Typ	Max	Unit
$T_{CLK-MISS}$	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.	---	---	60	ns
$T_{CLK-POST}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of THS-TRAIL to the beginning of TCLK-TRAIL.	$60 \text{ ns} + 52 \cdot UI$	---	---	ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	---	---	UI
$T_{CLK-PREPARE}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38	---	95	ns
$T_{CLK-SETTLE}$	Time interval during which the HS receiver shall ignore any Clock Lane HS transitions, starting from the beginning of TCLK-PREPARE.	95	---	300	ns



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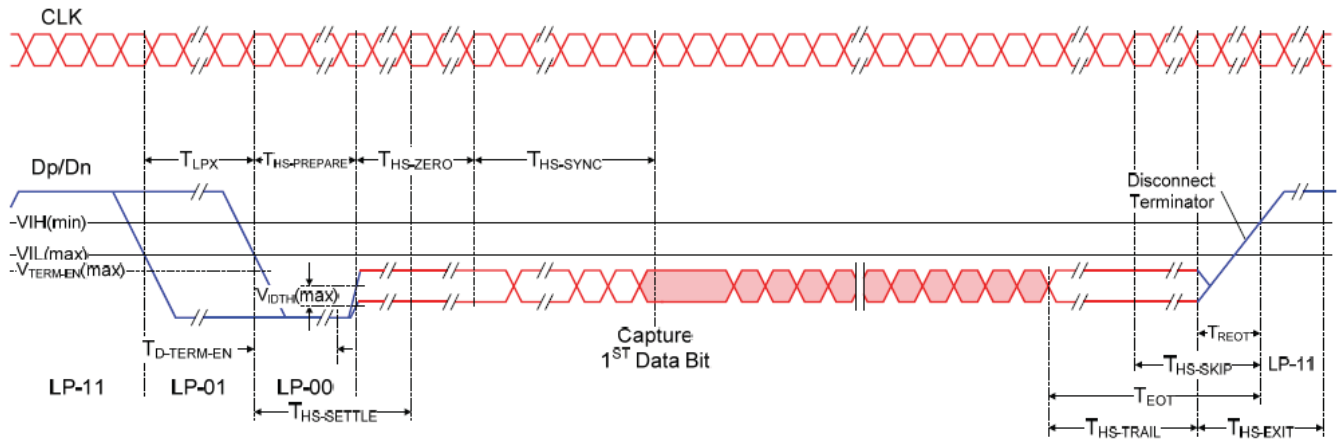
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$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses VIL,MAX.	Time for Dn to reach $V_{TERM-EN}$	---	38	ns
$T_{CLK-TRAIL}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60	---	---	ns
$T_{CLK-PREPARE} + T_{CLK-ZERO}$	TCLK-PREPARE + time that the transmitter drives the HS-0 state prior to starting the Clock.	300	---	---	ns
$T_{D-TERM-EN}$	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses VIL,MAX.	Time for Dn to reach $V_{TERM-EN}$	---	$35\text{ ns} + 4*UI$	ns
T_{EOT}	Transmitted time interval from the start of THS-TRAIL or TCLK-TRAIL, to the start of the LP-11 state following a HS burst.	---	---	$105\text{ ns} + 12*UI$	ns
$T_{HS-EXIT}$	Time that the transmitter drives LP-11 following a HS burst.	100	---	---	ns
$T_{HS-PREPARE}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	$40\text{ ns} + 4*UI$	---	$85\text{ ns} + 6*UI$	ns
$T_{HS-PREPARE} + T_{HS-ZERO}$	THS-PREPARE + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	$145\text{ ns} + 10*UI$	---	---	ns
$T_{HS-SETTLE}$	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of THS-PREPARE.	$85\text{ ns} + 6*UI$	---	$145\text{ ns} + 10*UI$	ns
$T_{HS-SKIP}$	Time interval during which the HS-RX should ignore any transitions on the Data Lane, following a HS burst. The end point of the interval is defined as the beginning of the LP-11 state following the HS burst.	40	---	$55\text{ ns} + 4*UI$	ns
$T_{HS-TRAIL}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	$\text{Max}(n*8*UI, 60\text{ns} + n*4*UI)$	---	---	ns
T_{INIT}		---	---	---	---
T_{LPX}	Transmitted length of any Low-Power state period	50			ns
Ratio T_{LPX}	Ratio of TLPX(MASTER)/TLPX(SLAVE) between Master and Slave side	2/3	---	3/2	
T_{TA-GET}	Time that the new transmitter drives the Bridge state (LP-00) after accepting control during a Link Turnaround.	$5*TLPX$			ns
T_{TA-GO}	Time that the transmitter drives the Bridge state (LP-00) before releasing control during a Link Turnaround.	$4*TLPX$			ns
$T_{TA-SURE}$	Time that the new transmitter waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	TLPX	---	$2*TLPX$	ns
T_{WAKEUP}	Time that a transmitter drives a Mark-1 state prior to a Stop state in order to initiate an exit from ULPS	1	---	---	ms

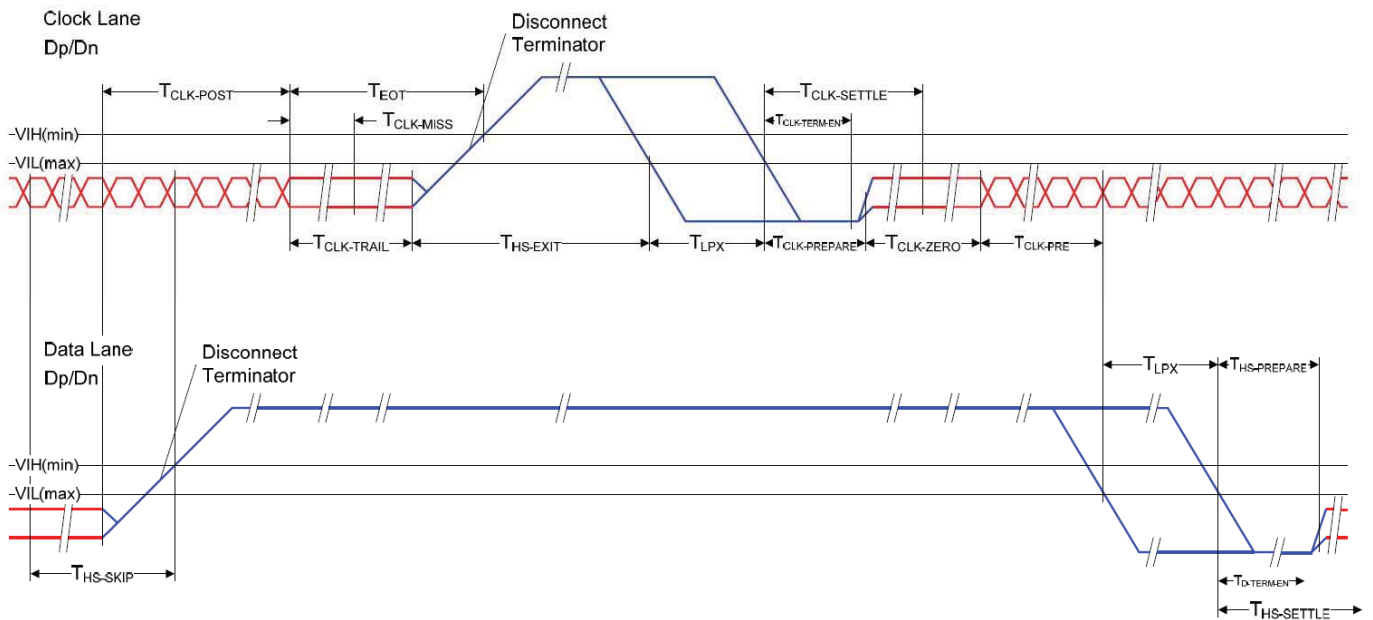
Note:

1. The minimum value depends on the bit rate. Implementations should ensure proper operation for all the supported bit rates.
2. TLPX is an internal state machine timing reference. Externally measured values may differ slightly from the specified values due to asymmetrical rise and fall times.

High-Speed Data Transmission in Bursts



Switching the Clock Lane between Clock Transmission and Low-Power Mode



5.2 Backlight Unit

5.2.1 LED characteristics

Parameter	Symbol	Min	Typ	Max	Units	Condition
Backlight Power Consumption	PLED	-	-	2.2	[Watt]	(Ta=25°C), Note 1 Vin =4.2V
LED Life-Time	N/A	15,000	-	-	Hour	(Ta=25°C), Note 2 If=20 mA

Note 1: Calculator value for reference $P_{LED} = V_F$ (Normal Distribution) * I_F (Normal Distribution) / Efficiency

Note 2: The LED life-time define as the estimated time to 50% degradation of initial luminous.

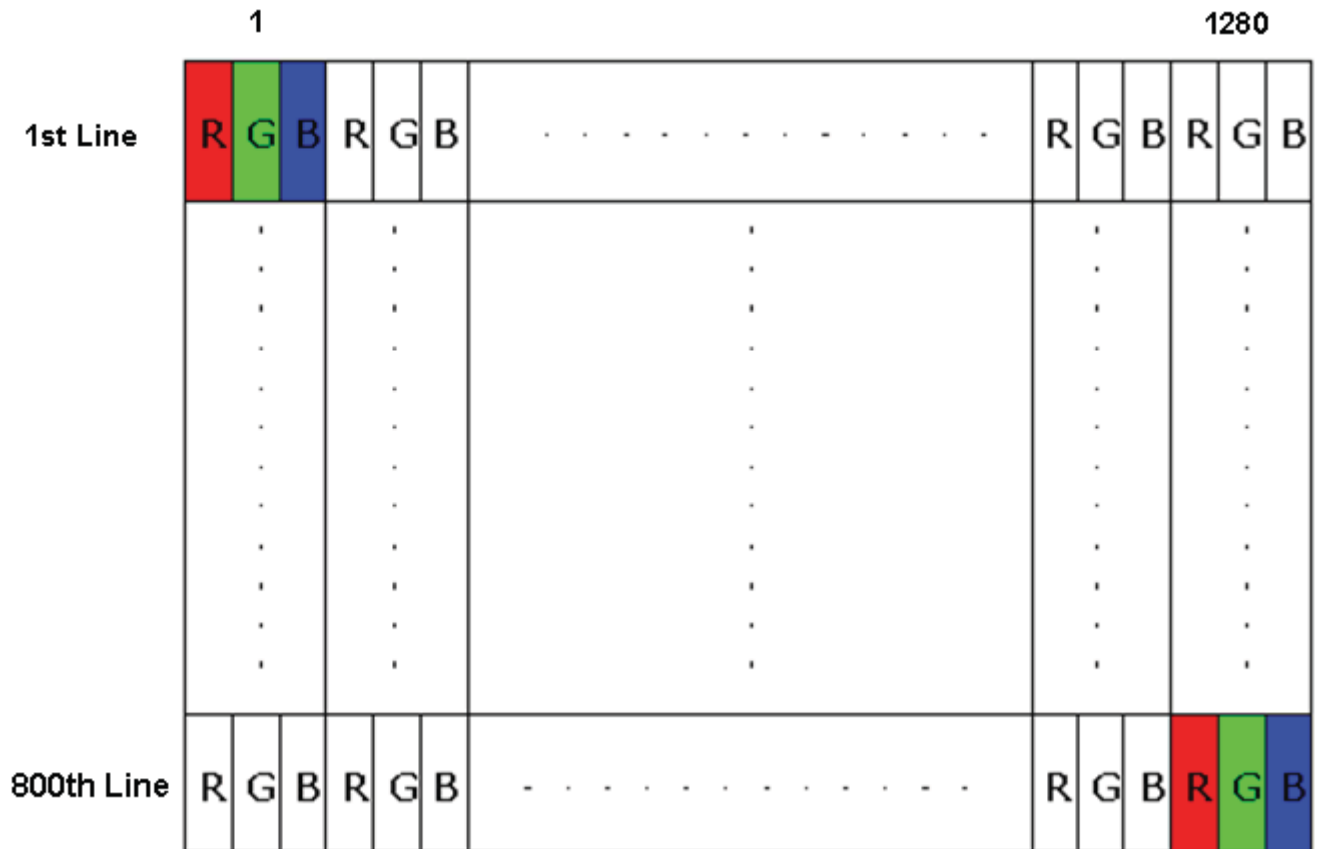
5.2.2 Backlight input signal characteristics

Parameter	Symbol	Min	Typ	Max	Units	Remark
LED Power Supply	VLED	3	5	13.8	[Volt]	Define as Connector Interface (Ta=25°C)
LED Enable Input High Level	LED_EN	2.4	-	5.0	[Volt]	
LED Enable Input Low Level		-	-	0.8	[Volt]	
PWM Logic Input High Level	LED_PWM	2.4	-	5.0	[Volt]	
PWM Logic Input Low Level		-	-	0.8	[Volt]	
PWM Input Frequency	FPWM	700	1K	2K	Hz	
PWM Duty Ratio	Duty	1	--	100	%	

6. Signal Interface Characteristic

6.1 Pixel Format Image

Following figure shows the relationship of the input signals and LCD pixel format.



6.2 Integration Interface Requirement

6.2.1 MIPI Connector Description

Physical interface is described as for the connector on module.

These connectors are capable of accommodating the following signals and will be following components.

Connector Name / Designation	For Signal Connector
Manufacturer	HIROSE
Type / Part Number	FH34SJ-34S-0.5SH(50)
Mating Housing/Part Number	FPC Cable

6.2.2 MIPI Pin Assignment

MIPI is a differential signal technology for LCD interface and high speed data transfer device.

No.	Pin Name	Description
1	VDD	DC-DC circuit supply voltage (3.1V~3.6V)
2	VDD	DC-DC circuit supply voltage (3.1V~3.6V)
3	NC	Not Connection
4	LED_EN	LED driver Enable Input (VIH=1.8V)
5	LED_PWM	Backlight LED driver PWM Input (VIH=1.8V)
6	EDID_SDA	EDID Data Input (VIH=VDD*0.7)
7	EDID_SCL	EDID Clock Input (VIH=VDD*0.7)
8	NC	Not Connection
9	GND	Ground
10	DSI_D2P/Rx-IN2P	MIPI data pair 2 positive signal
11	DSI_D2N/Rx-IN2N	MIPI data pair 2 negative signal
12	GND	Ground
13	DSI_D1P/Rx-IN1P	MIPI data pair 1 positive signal
14	DSI_D1N/Rx-IN1N	MIPI data pair 1 negative signal
15	GND	Ground
16	DSI_CLKP/Rx-CLKP	MIPI Clock positive signal
17	DSI_CLKN/Rx-CLKN	MIPI Clock negative signal
18	GND	Ground
19	DSI_D0P/Rx-IN0P	MIPI data pair 0 positive signal
20	DSI_D0N/Rx-IN0N	MIPI data pair 0 negative signal
21	GND	Ground
22	DSI_D3P/Rx-IN3P	MIPI data pair 3 positive signal
23	DSI_D3N/Rx-IN3N	MIPI data pair 3 negative signal



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24	GND	Ground
25	GND	Ground
26	GND	Ground
27	GND	Ground
28	GND	Ground
29	Aging	Aging Mode Power Supply (AUO only)
30	NC	Not Connection
31	LED+	LED Power Supply (3V – 13.8V)
32	LED+	LED Power Supply (3V – 13.8V)
33	LED+	LED Power Supply (3V – 13.8V)
34	LED+	LED Power Supply (3V – 13.8V)

PS. EDID_SDA/SCL must be GND except the period of EDID reading

6.3 MIPI Interface Timing

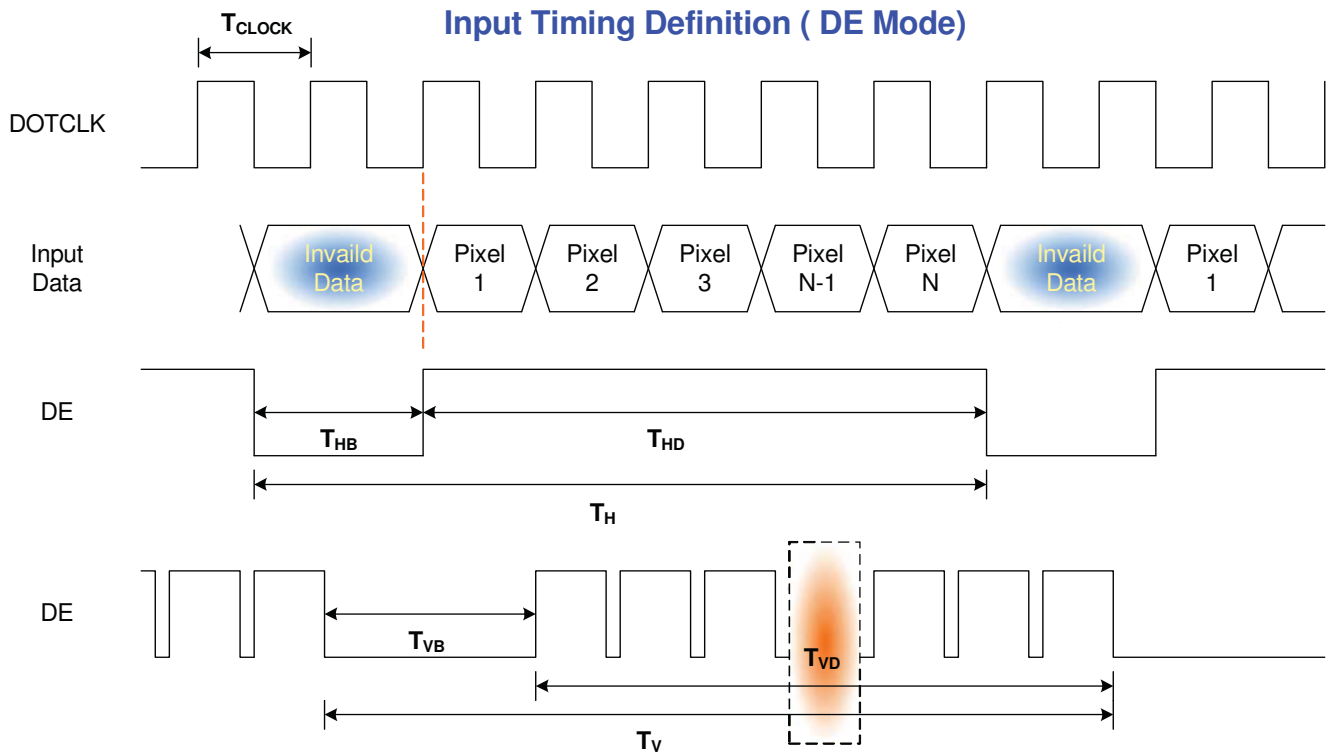
6.3.1 Timing Characteristics

Basically, interface timings should match the 1280x800 /60Hz manufacturing guide line timing.

Parameter		Symbol	Min.	Typ.	Max.	Unit
Frame Rate		---	---	60	---	Hz
Clock frequency		1/ T _{Clock}	64	72.46	85	MHz
Vertical Section	Period	T _V	808	816	1023	T _{Line}
	Active	T _{VD}	800			
	Blanking	T _{VB}	8	16	223	
Horizontal Section	Period	T _H	1340	1480	2047	T _{Clock}
	Active	T _{HD}	1280			
	Blanking	T _{HB}	60	200	767	

Note : DE mode only

6.3.2 Timing diagram



6.4 Power ON/OFF Sequence

Power on/off sequence is as follows. Interface signals and LED on/off sequence are also shown in the chart. Signals from any system shall be Hi-Z state or low level when VDD is off

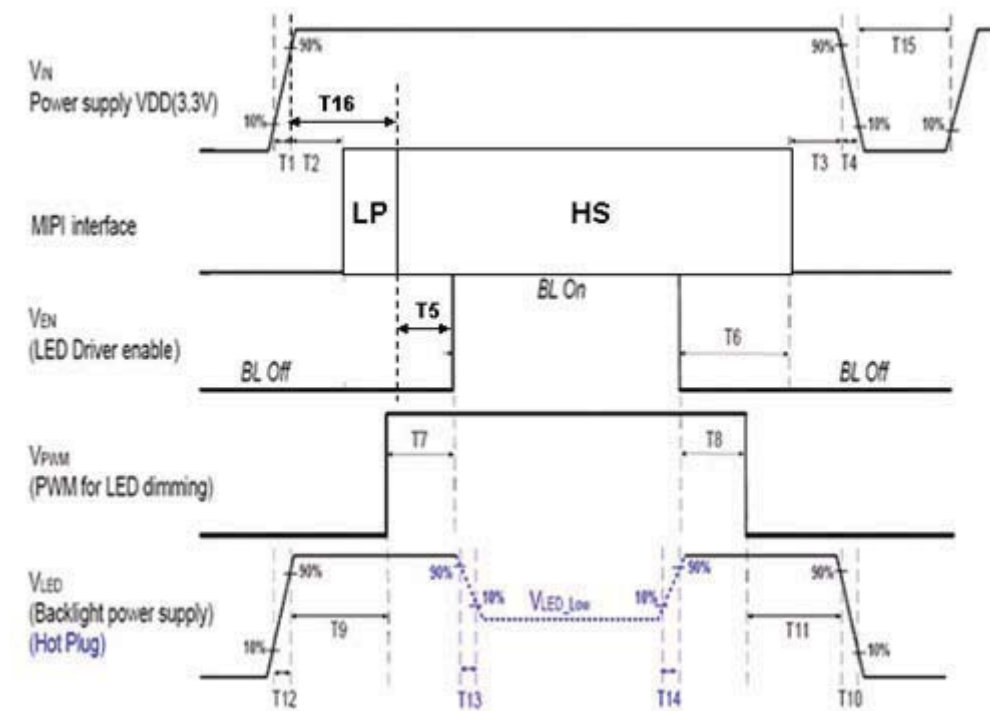


Figure 22 Power On/Off Sequence

ALLIED 3 Series on battery 2017

Parameter	Value		Units
	Min.	Max.	
T1	0.5	10	ms
T2	30		
T3	50	-	
T4	0.5	10	
T5	20	-	
T6	20	-	
T7	10	-	
T8	10	-	
T9	10	-	
T10	0.5	10	
T11	10	-	
T12	0.5	10	
T13	K	-	
T14	K	-	
T15	500	-	
T16	90	-	

Noraml : K=1, No Flash: K=5xTpwm

* Tpwm =1/PWM Frequecny

7. Panel Reliability Test

7.1 Vibration Test

Test Spec:

- Test method: Non-Operation
- Acceleration: 1.5 G
- Frequency: 10 - 500Hz Random
- Sweep: 30 Minutes each Axis (X, Y, Z)

7.2 Shock Test

Test Spec:

- Test method: Non-Operation
- Acceleration: 220 G , Half sine wave
- Active time: 2 ms
- Pulse: X,Y,Z .one time for each side

7.3 Reliability Test

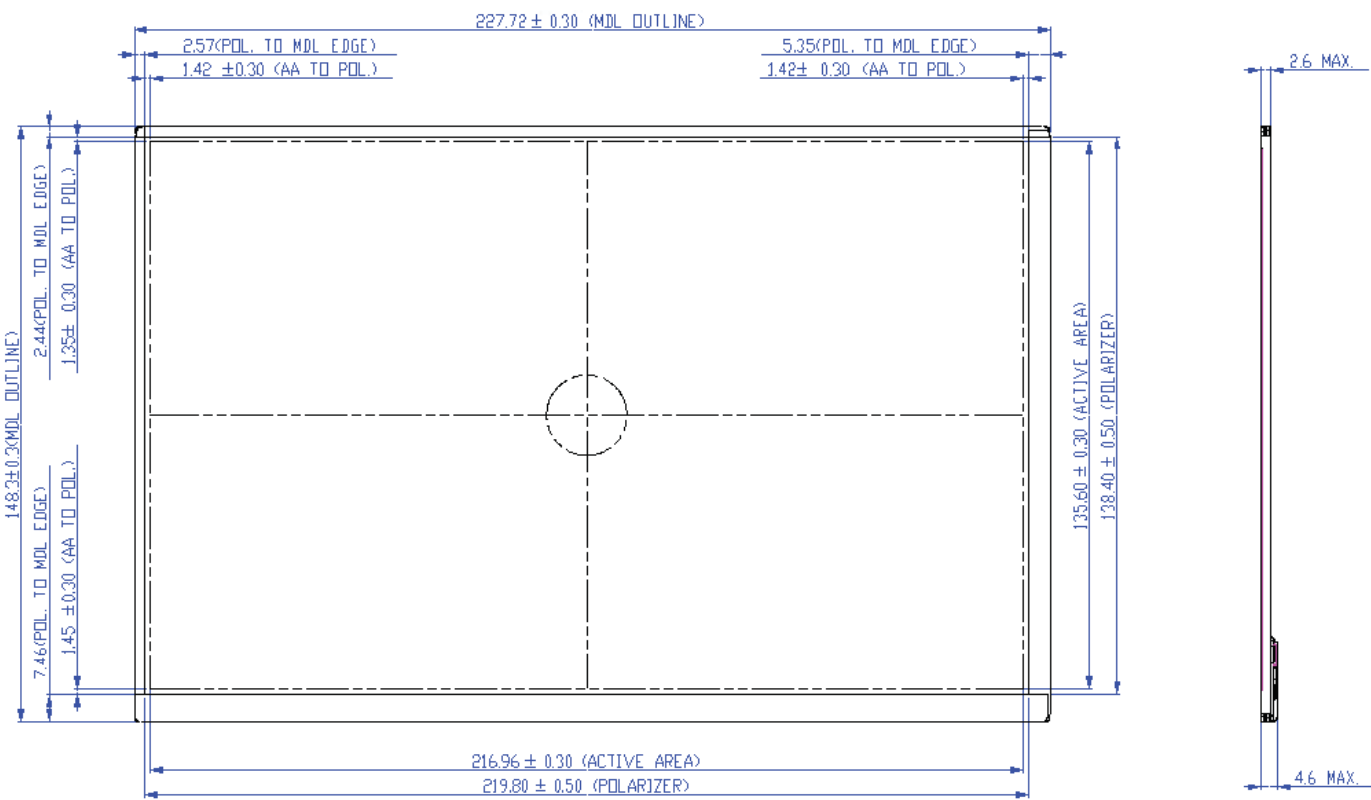
Items	Required Condition	Note
Temperature Humidity Bias	Ta= 40°C , 90%RH, 300h	
High Temperature Operation	Ta= 50°C , Dry, 300h	
Low Temperature Operation	Ta= 0°C , 300h	
High Temperature Storage	Ta= 60°C , 300h	
Low Temperature Storage	Ta= -20°C , 300h	
Thermal Shock Test	Ta=-20°C to 60°C , Duration at 30 min, 100 cycles	
ESD	Contact : ±8 KV Air : ±15 KV	Note 1

Note1: According to EN 61000-4-2 , ESD class B: Some performance degradation allowed. No data lost
. Self-recoverable. No hardware failures.

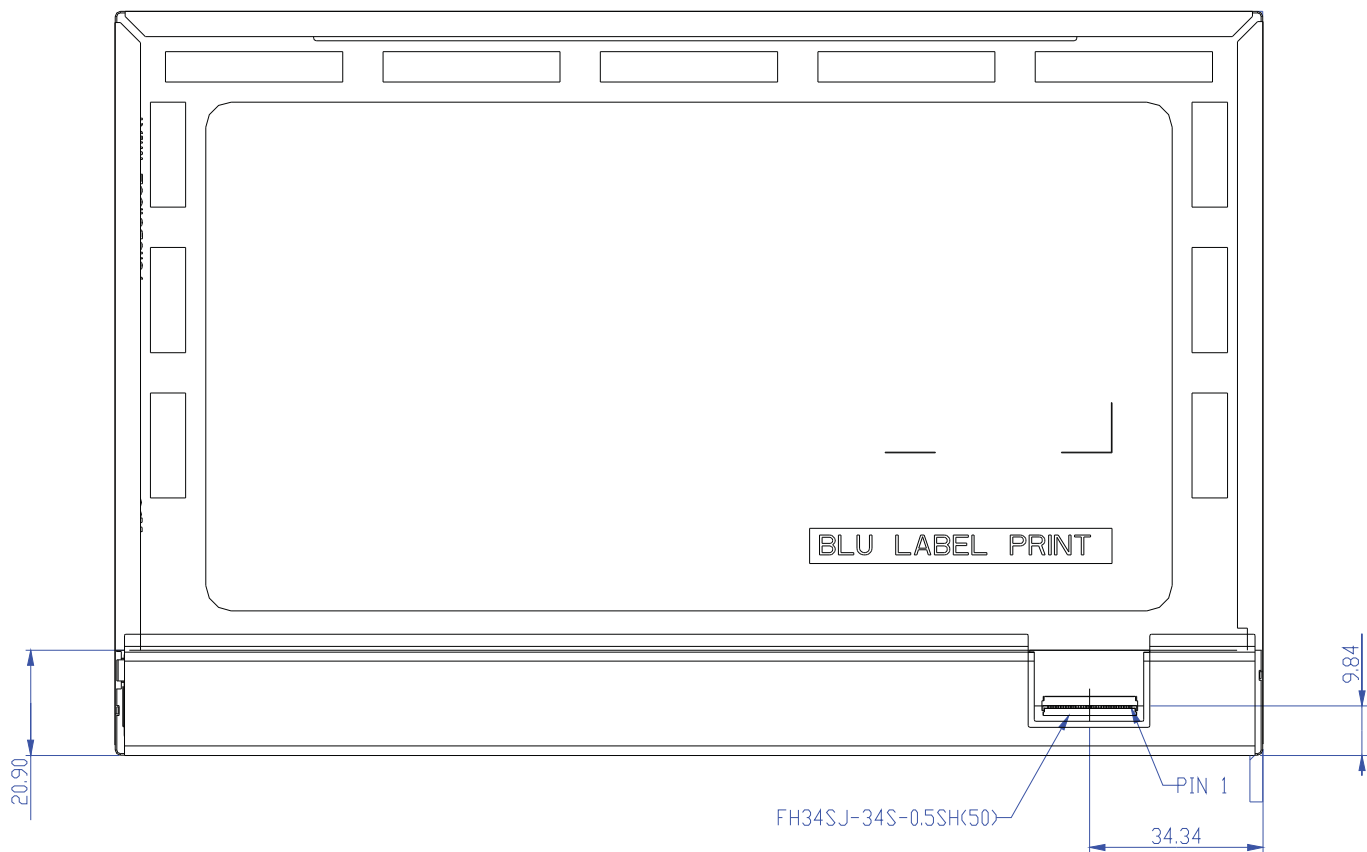
Remark: MTBF (Excluding the LED): 30,000 hours with a confidence level 90%

8. Mechanical Characteristics

8.1 Standard Front View



8.2 Standard Rear View



Note : Back Bezel (Material : SUS 304 ; 0.2mm)

9. Shipping and Package

9.1 Shipping Label Format

 *XXXXXXXXXXXX-XXXXX	Manufactured YYWW Model No: B101EAN01.5 AU Optronics Made in China (S01) H/W: 0A F/W:0	
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 *XXXXXXXXXXXX-XXXXX	Manufactured YYWW Model No: B101EAN01.5 AU Optronics Made in China (S06) H/W: 0A F/W:0	
--	---	---

9.2 Carton Label Format

AU Optronics	QTY : 60	
MODEL NO : B101EAN01.5		
PART NO : 97.10B51.5XX		
CUSTOMER NO :		
CARTON NO :		
 XXXXXX-XXXXXXXXXXXX		
MADE IN CHINA		

10. Appendix

10.1 EDID Description

B101EAN01 5 EDID Code

Address	FUNCTION	Value	Value	Value	Note
HEX		HEX	BIN	DEC	
00	Header	00	00000000	0	
01		FF	11111111	255	
02		FF	11111111	255	
03		FF	11111111	255	
04		FF	11111111	255	
05		FF	11111111	255	
06		FF	11111111	255	
07		00	00000000	0	
08	EISA Manuf. Code LSB	06	00000110	6	
09	Compressed ASCII	AF	10101111	175	
0A	Product Code	D4	11010100	212	
0B	hex, LSB first	15	00010101	21	
0C	32-bit ser #	00	00000000	0	
0D		00	00000000	0	
0E		00	00000000	0	
0F		00	00000000	0	
10	Week of manufacture	23	00100011	35	
11	Year of manufacture	17	00010111	23	
12	EDID Structure Ver.	01	00000001	1	
13	EDID revision #	04	00000100	4	
14	Video input def. (digital I/P, non-TMDS, CRGB)	A0	10100000	160	
15	Max H image size (rounded to cm)	16	00010110	22	
16	Max V image size (rounded to cm)	0E	00001110	14	
17	Display Gamma $(=(\text{gamma} \times 100) - 100)$	78	01111000	120	
18	Feature support (no DPMS, Active OFF, RGB, tmg Blk#1)	02	00000010	2	
19	Red/green low bits (Lower 2:2:2:2 bits)	99	10011001	153	
1A	Blue/white low bits (Lower 2:2:2:2 bits)	85	10000101	133	
1B	Red x (Upper 8 bits)	95	10010101	149	
1C	Red y/ highER 8 bits	55	01010101	85	
1D	Green x	56	01010110	86	
1E	Green y	92	10010010	146	
1F	Blue x	28	00101000	40	
20	Blue y	22	00100010	34	
21	White x	50	01010000	80	
22	White y	54	01010100	84	
23	Established timing 1	00	00000000	0	
24	Established timing 2	00	00000000	0	
25	Established timing 3	00	00000000	0	
26	Standard timing #1	01	00000001	1	

27		01	00000001	1	
28	Standard timing #2	01	00000001	1	
29		01	00000001	1	
2A	Standard timing #3	01	00000001	1	
2B		01	00000001	1	
2C	Standard timing #4	01	00000001	1	
2D		01	00000001	1	
2E	Standard timing #5	01	00000001	1	
2F		01	00000001	1	
30	Standard timing #6	01	00000001	1	
31		01	00000001	1	
32	Standard timing #7	01	00000001	1	
33		01	00000001	1	
34	Standard timing #8	01	00000001	1	
35		01	00000001	1	
36	Pixel Clock/10000 LSB	52	01010010	82	
37	Pixel Clock/10000 USB	1C	00011100	28	
38	Horz active Lower 8bits	00	00000000	0	
39	Horz blanking Lower 8bits	C8	11001000	200	
3A	HorzAct:HorzBlnk Upper 4:4 bits	50	01010000	80	
3B	Vertical Active Lower 8bits	20	00100000	32	
3C	Vertical Blanking Lower 8bits	10	00010000	16	
3D	Vert Act : Vertical Blanking (upper 4:4 bit)	30	00110000	48	
3E	HorzSync. Offset	93	10010011	147	
3F	HorzSync.Width	20	00100000	32	
40	VertSync.Offset : VertSync.Width	44	01000100	68	
41	Horz&Vert Sync Offset/Width Upper 2bits	00	00000000	0	
42	Horizontal Image Size Lower 8bits	D8	11011000	216	
43	Vertical Image Size Lower 8bits	87	10000111	135	
44	Horizontal & Vertical Image Size (upper 4:4 bits)	00	00000000	0	
45	Horizontal Border <i>(zero for internal LCD)</i>	00	00000000	0	
46	Vertical Border <i>(zero for internal LCD)</i>	00	00000000	0	
47	Signal <i>(non-intr, norm, no stero, sep sync, neg pol)</i>	18	00011000	24	
48	Detailed timing/monitor	00	00000000	0	
49	descriptor #2	00	00000000	0	
4A		00	00000000	0	
4B		0F	00001111	15	
4C		00	00000000	0	
4D		00	00000000	0	
4E		00	00000000	0	
4F		00	00000000	0	
50		00	00000000	0	
51		00	00000000	0	
52		00	00000000	0	

53		00	00000000	0	
54		00	00000000	0	
55		00	00000000	0	
56		00	00000000	0	
57		00	00000000	0	
58		00	00000000	0	
59		20	00100000	32	
5A	Detailed timing/monitor	00	00000000	0	
5B	descriptor #3	00	00000000	0	
5C		00	00000000	0	
5D		FE	11111110	254	
5E		00	00000000	0	
5F	Manufacture	41	01000001	65	A
60	Manufacture	55	01010101	85	U
61	Manufacture	4F	01001111	79	O
62		0A	00001010	10	
63		20	00100000	32	
64		20	00100000	32	
65		20	00100000	32	
66		20	00100000	32	
67		20	00100000	32	
68		20	00100000	32	
69		20	00100000	32	
6A		20	00100000	32	
6B		20	00100000	32	
6C	Detailed timing/monitor	00	00000000	0	
6D	descriptor #4	00	00000000	0	
6E		00	00000000	0	
6F		FE	11111110	254	
70		00	00000000	0	
71	Manufacture P/N	42	01000010	66	B
72	Manufacture P/N	31	00110001	49	1
73	Manufacture P/N	30	00110000	48	0
74	Manufacture P/N	31	00110001	49	1
75	Manufacture P/N	45	01000101	69	E
76	Manufacture P/N	41	01000001	65	A
77	Manufacture P/N	4E	01001110	78	N
78	Manufacture P/N	30	00110000	48	0
79	Manufacture P/N	31	00110001	49	1
7A	Manufacture P/N	2E	00101110	46	.
7B	Manufacture P/N	35	00110101	53	5
7C		20	00100000	32	
7D		0A	00001010	10	
7E	Extension Flag	00	00000000	0	

7F	Checksum	D9	11011001	217
SUM			6400	
SUM to HEX			1900	